deposing a first wire in a first Manhattan direction relative to the boundaries of the integrated circuit, the first wire comprising a first wire length including first and second ends;

deposing a second wire in a second Manhattan direction relative to the boundaries of the integrated circuit, the second wire comprising a second wire length including first and second ends;

coupling the first end of the second wire to the second end of the first wire; and

wherein, an effective direction of the pairs of conductors comprises an angle, A, measured relative to the boundaries of the integrated circuit, defined by the expression Tan A = Y/X,

wherein, Y comprises a line segment with a distance starting from the second end of the second wire in the last conductor pair and ending at an intersection with a line segment propagated from the first end of the first wire and in the direction of the first wire, and - X comprises a distance, measured in the direction of the first wire, starting from the first end of the first wire and ending with the intersection of the Y line segment.

[c43]

43.The method as set forth in claim 42, wherein the first Manhattan direction comprises a horizontal direction and the second Manhattan direction comprises a vertical direction.

[c44]

44.The method as set forth in claim 42, wherein the first Manhattan direction comprises a vertical direction and the second Manhattan direction comprises a horizontal direction.

[c45]

45.The method as set forth in claim 42, wherein the first wire length equals the second wire length, so as to simulate an effective direction of 45 degrees.

[c46]

46.The method as set forth in claim 42, wherein the ratio of the first wire length to the second wire length equals three to two, so as to simulate an effective wiring direction of 60 degrees.

[c47]

47.The method as set forth in claim 42, further comprising the step deposing a plurality of independent conductors in parallel.

Abstract of Disclosure